

Process Change Notice

Parts Affected:

Schottky diodes manufactured in the SOD-123, SOT-23, and SOT-323 packages and Transient Voltage Suppressors manufactured in the SOT-23 package.

Extent of Change:

Tin (Sn) wafer backside metal has been added as a qualified material in addition to the currently used gold (Au) backside metal.

Reason for Change:

This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

Effect of Change:

This change does not affect the form, fit, or function of any device. Devices assembled with gold backside metal will continue to be manufactured concurrently with devices assembled with tin backside metal.

Qualification:

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:

August 1, 2010.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Part Numbers Affected:

CMHSH5-2L
CMPSH-3
CMPSH-3A
CMPSH-3C
CMPSH-3S
CMSSH-3
CMSSH-3A
CMSSH-3C
CMSSH-3S
CSL05D